

规格书编号

SPEC NO:

产品规格书 SPECIFICATION

CUSTOMER 客户:_							
PRODUCT 产品:_	TUNING FORK						
MODEL NO 型 号:_	TF38-32.768-12.5-10-LF						
PREPARED 编 制: _	LEO CHECKED 审 核: YORK						
APPROVED 批 准:_	LIUMING	DATE 日 期	明: 2014-6-20				
客户确认 CUSTOMER RECEIVED:							
审核 CHECKED	批准	APPROVED	日期 DATE				

无锡市好达电子股份有限公司 Shoulder Electronics Limited

更改历史记录 History Record

更改日期 Date	规格书编号 Spec No	产品型号 Part No	客户产品型号 Customer No	更改内容描述 Modify Content	备注 Remark

CRYSTAL SEPECIFICATION

1. Description: Tuning Fork Quartz Crystal

Nominal Frequency: 32.768KHz
 Oscillation Mode: Fundamental

4. Cutting Mode: AT cut

5. Measurement Instrument: S&A 250B(Measured FL)

6. Electrical Characteristics: [1]Operation Conditions:

Item	Symbol	MIN.	TYP.	MAX.	Unit	Condition
Operating Temperature Range	Topt	-10		60	$^{\circ}$	
Storage Temperature Range	Tstg	-40		85	$^{\circ}$	
Load Capacitance	CL		12.5		рF	
Drive Level	DL		0.1	1	uW	

[2]Frequency Stability:

Item	Symbol	MIN.	TYP.	MAX.	Unit	Condition
Tolerance	dF/Fo	-10		10	ppm	Refer to Center Frequency@25±3°C
Stability Over Temperature	dF/F25		-0.036		ppm/°C²	Refer to Operating Temperature
Aging	dF/F25	-5		5	ppm	Per Year

dF/Fo:Frequency Deviation Refer to Center Frequency

dF/F25:Frequency Deviation Refer to 25°C Frequency

[3] Electrical Performance:

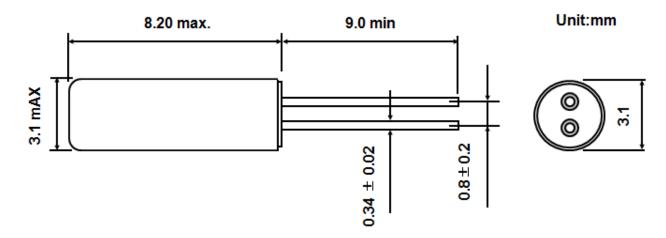
Item	Symbol	MIN.	TYP.	MAX.	Unit	Condition
Equivalent Series Resistance	ESR			50	ΚΩ	@ Series
Shunt Capacitance	C0		1	5	pF	
Insulation Resistance	IR	500			ΜΩ	@DC 100 Volt

7. Marking:Laser

Marking Generally for empty. Refer to with Customer's requirement.

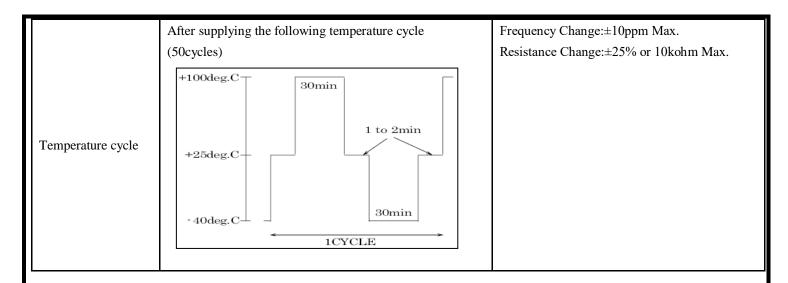
32.768

8. Outline drawing (unit: mm)



9. Reliability Specification

Test Items	Test Method and Condition	Requirements
Vibration	(1)Vibration Frequency 10 to 55Hz (2)Vibration Amplitude 1.5mm (3) Cycle Time 1-2min(10-55-10Hz) (4)Direction X.Y.Z (5)Duration 2h/each direction	Frequency Change:±10ppm Max. Resistance Change:±15% or 5kohm Max.
Shock	3 Times free drop from 75cm height to hard wooden board of thickness more than 30mm	Frequency Change:±10ppm Max. Resistance Change:±15% or 5kohm Max.
Hermetic seal	Helium leak detector Checked:before the molded crystal uints	less than 1 × 10 EXP(-7) mbar.l/sec.
Solder ability	Dip the leads of crystal units into the solution (7-10%) of rosin 3 \pm 0.5s,then dip it into the tank 5-10s. Temperature of solder melted tank is 245 °C \pm 5 °C	The dipped surface of the leads should be at least 95% covered with continuous new solder coating
High temperature	240 hours at +85 °C \pm 2 °C After 1-2hours past at room temperature from following	Frequency Change:±10ppm Max. Resistance Change:±25% or 10kohm Max.
Low temperature	240 hours at -20°C±2°C After 1-2hours past at room temperature from following test.	Frequency Change:±10ppm Max. Resistance Change:±15% or 5kohm Max.
Humidity	240 hours at +40°C±2°C,relative humidity 90-95% After 1-2hours past at room temperature from following	Frequency Change:±10ppm Max. Resistance Change:±25% or 10kohm Max.



10. Handling Notice for Standard Tuning Fork Crystal (Cylindrical Type)

1. Shock resistance

It may deteriorate the characteristics or cause of no oscillation if excess physical shock given. Please be careful not to drop. Please use under condition to minimize the shocks as much as possible.

Please review the conditions if it is used by auto mounting or after the conditions are changed.

2. Heat and humidity resistance in storage

Storing the crystal products under higher or lower temperature or high humidity for a long period may deteriorate the characteristics of crystal units.

Please store and use the crystal products at the normal temperature and humidity.

3. Solder heat resistance

Standard type crystal products use Material have a 230°C melting point.

Heating up the package more than 210°C may deteriorate the characteristics or cause of no oscillation the products. If the crystal products need to be soldered at temperature of more than +210°C, please study heat-resistance products or SMD products.

Please review the condition or consult us about flow solder process.

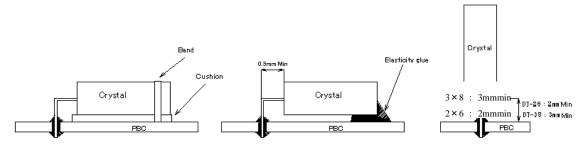
Our soldering condition is under 280°C within 5sec or 260°C within 10sec for lead parts. Please don't solder the crystal unit (case) directly. It may cause of deteriorate the characteristics.

4. Mounting method to PCB

When the crystal products need to be lay down please fix to PCB securely.

If the crystal is used with mechanical vibration location, please put cushion in between PCB or fix with elasticity glue (Silicon etc) as shown in below figure. Please don't gluing hermetic seal grass.

When the crystal products need to be mounted vertically, gap between crystal units and PCB more than 3mm for 3×8 type, more than 2mm for 2×6 type is recommended.



5. Lead process

When the lead needs to be cut please maintenance the cutter.

When the lead needs to be bent or repaired please be careful not to giving excess pressure at the root of the lead to avoid crack of the hermetic seal glass. Also please be careful not to giving excess pressure at sealing to avoid sealing tightness deteriorate.

Leave more than 0.5 mm of lead from the case.

Ultrasonic cleaning and ultrasonic soldering

Soldered by ultrasonic cannot be guaranteed, because crystal may be sympathetic vibrated and may damage.

Please study at your side about ultrasonic cleaning.

6. Drive level

Applying excessive drive level to the crystal units may cause deterioration of characteristics or damage. Less then $1.0\mu W$ is recommended to this products. More than $2.0\mu W$ cannot be guaranteed.

REVIEW OF SPECIFICATION

When something get doubtful with this specifications, we shall jointly work to get an agreement.

11. Packing Description

1000pcs/bag

10000pcs/box (175*120*65)

100000pcs/big box (300*180*600)